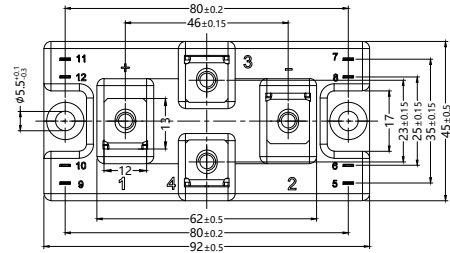
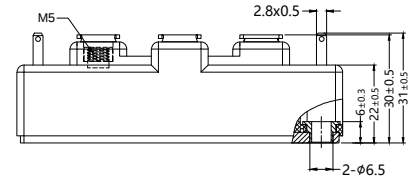


# S4G25T120SC9

## H bridge IGBT modules



Dimension: mm

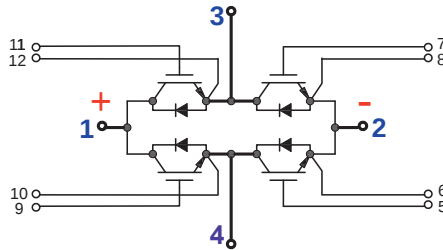


$V_{CES} = 1200V$

$I_{C100} = 4 \times 25A$

$V_{CESat(typ)} = 2.00V$

$E_{off(typ)} = 0.65mJ$



### Absolute Maximum Ratings

| Symbol              | Test Conditions                                                                |                       | Values       | Unit |
|---------------------|--------------------------------------------------------------------------------|-----------------------|--------------|------|
| IGBT                |                                                                                |                       |              |      |
| V <sub>CES</sub>    | T <sub>j</sub> =25°C                                                           |                       | 1200         | V    |
| I <sub>C</sub>      | T <sub>j</sub> = 175 °C                                                        | T <sub>C</sub> =25°C  | 50           | A    |
|                     |                                                                                | T <sub>C</sub> =80°C  | 25           | A    |
| I <sub>Cnom</sub>   | T <sub>C</sub> = 100 °C Every chip                                             |                       | 25           | A    |
| I <sub>CRM</sub>    | I <sub>CRM</sub> = 3xI <sub>Cnom</sub>                                         |                       | 75           | A    |
| V <sub>GES</sub>    |                                                                                |                       | -20 ... +20  | V    |
| tpsc                | V <sub>CC</sub> = 600 V<br>V <sub>GE</sub> ≤ 15 V<br>V <sub>CES</sub> ≤ 1200 V | T <sub>j</sub> =150°C | 10           | μs   |
| T <sub>j</sub>      |                                                                                |                       | -40 ... +150 | °C   |
| Inverse diode       |                                                                                |                       |              |      |
| I <sub>F</sub>      | T <sub>j</sub> = 175 °C                                                        | T <sub>c</sub> =25°C  | 40           | A    |
|                     |                                                                                | T <sub>c</sub> =80°C  | 20           | A    |
| I <sub>Fnom</sub>   |                                                                                |                       | 40           | A    |
| I <sub>FRM</sub>    | I <sub>FRM</sub> = 3xI <sub>Fnom</sub>                                         |                       | 120          | A    |
| I <sub>FSM</sub>    | t <sub>p</sub> = 10 ms, sin 180°, T <sub>j</sub> =25°C                         |                       | 90           | A    |
| T <sub>j</sub>      |                                                                                |                       | -40 ... +150 | °C   |
| Module              |                                                                                |                       |              |      |
| I <sub>t(RMS)</sub> | T <sub>terminal</sub> =80°C                                                    |                       | 125          | A    |
| T <sub>stg</sub>    |                                                                                |                       | -40 ... 125  | °C   |
| V <sub>Isol</sub>   | AC sinus 50 Hz, t = 1 min                                                      |                       | 4000         | V    |

**Sirectifier®**

# S4G25T120SC9

## H bridge IGBT modules

| Characteristics      |                                                                                                                                                                                              |                       |       |      |       |      |
|----------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------|-------|------|-------|------|
| Symbol               | Test Conditions                                                                                                                                                                              |                       | min.  | typ. | max.  | Unit |
| IGBT                 |                                                                                                                                                                                              |                       |       |      |       |      |
| V <sub>CE(sat)</sub> | I <sub>C</sub> =25A<br>V <sub>GE</sub> =15V<br>chip level                                                                                                                                    | T <sub>j</sub> =25°C  | 2.00  |      | 2.45  | V    |
|                      |                                                                                                                                                                                              | T <sub>j</sub> =150°C | 2.60  |      |       | V    |
| V <sub>CE0</sub>     | chiplevel                                                                                                                                                                                    | T <sub>j</sub> =25°C  | 0.8   |      | 0.9   | V    |
|                      |                                                                                                                                                                                              | T <sub>j</sub> =150°C | 0.7   |      | 0.8   | V    |
| r <sub>CE</sub>      | V <sub>GE</sub> =15V                                                                                                                                                                         | T <sub>j</sub> =25°C  | 14.00 |      | 16.00 | mΩ   |
|                      | chiplevel                                                                                                                                                                                    | T <sub>j</sub> =150°C | 21.00 |      | 22.00 | mΩ   |
| V <sub>GE(th)</sub>  | V <sub>GE</sub> =V <sub>CE</sub> , I <sub>C</sub> = 1.7 mA                                                                                                                                   |                       | 5     | 5.8  | 6.5   | V    |
| I <sub>CES</sub>     | V <sub>GE</sub> =0V                                                                                                                                                                          | T <sub>j</sub> =25°C  |       |      | 0.1   | mA   |
|                      | V <sub>CE</sub> = 1200 V                                                                                                                                                                     | T <sub>j</sub> =150°C |       |      | 1     | mA   |
| C <sub>ies</sub>     | V <sub>CE</sub> =25V<br>V <sub>GE</sub> =0V                                                                                                                                                  | f=1MHz                | 1.80  |      |       | nF   |
| C <sub>oes</sub>     |                                                                                                                                                                                              | f=1MHz                | 0.07  |      |       | nF   |
| C <sub>res</sub>     |                                                                                                                                                                                              | f=1MHz                | 0.045 |      |       | nF   |
| Q <sub>G</sub>       | V <sub>GE</sub> = - 8 V...+ 15 V                                                                                                                                                             |                       | 140   |      |       | nC   |
| R <sub>Gint</sub>    | T <sub>j</sub> =25°C                                                                                                                                                                         |                       | 4.0   |      |       | Ω    |
| t <sub>d(on)</sub>   | V <sub>CC</sub> = 600 V<br>I <sub>C</sub> =25A<br>V <sub>GE</sub> =±15V<br>R <sub>Gon</sub> =1Ω<br>R <sub>Goff</sub> =1Ω<br>di/dt <sub>on</sub> = 1700 A/μs<br>di/dt <sub>off</sub> =670A/μs | T <sub>j</sub> =25°C  | 61    |      |       | ns   |
| t <sub>r</sub>       |                                                                                                                                                                                              | T <sub>j</sub> =25°C  | 22    |      |       | ns   |
| E <sub>on</sub>      |                                                                                                                                                                                              | T <sub>j</sub> =25°C  | 3.3   |      |       | mJ   |
| t <sub>d(off)</sub>  |                                                                                                                                                                                              | T <sub>j</sub> =25°C  | 295   |      |       | ns   |
| t <sub>f</sub>       |                                                                                                                                                                                              | T <sub>j</sub> =25°C  | 94    |      |       | ns   |
| E <sub>off</sub>     |                                                                                                                                                                                              | T <sub>j</sub> =25°C  | 0.65  |      |       | mJ   |
| R <sub>th(j-c)</sub> | per IGBT                                                                                                                                                                                     |                       |       |      | 0.66  | K/W  |



# S4G25T120SC9

## H bridge IGBT modules

| Characteristics                  |                                                           |                         |      |      |      |      |
|----------------------------------|-----------------------------------------------------------|-------------------------|------|------|------|------|
| Symbol                           | Test Conditions                                           |                         | min. | typ. | max. | Unit |
| Inverse diode                    |                                                           |                         |      |      |      |      |
| V <sub>F</sub> = V <sub>EC</sub> | I <sub>F</sub> = 20 A                                     | T <sub>j</sub> = 25 °C  | 1.90 | 2.54 |      | V    |
|                                  | V <sub>GE</sub> = 0 V<br>chiplevel                        | T <sub>j</sub> = 150 °C | 2.08 | 2.60 |      | V    |
| V <sub>F0</sub>                  | chiplevel                                                 | T <sub>j</sub> = 25 °C  | 1.3  | 1.5  |      | V    |
|                                  |                                                           | T <sub>j</sub> = 150 °C | 0.9  | 1.1  |      | V    |
| r <sub>F</sub>                   | chiplevel                                                 | T <sub>j</sub> = 25 °C  | 18.0 | 20.0 |      | mΩ   |
|                                  |                                                           | T <sub>j</sub> = 150 °C | 25.0 | 28.0 |      | mΩ   |
| I <sub>RRM</sub>                 | I <sub>F</sub> = 20 A<br>di/dt <sub>off</sub> = 1380 A/μs | T <sub>j</sub> = 150 °C | 20   |      |      | A    |
| Q <sub>rr</sub>                  | V <sub>GE</sub> = ±15 V                                   | T <sub>j</sub> = 150 °C | 8.0  |      |      | μC   |
| E <sub>rr</sub>                  | V <sub>CC</sub> = 600 V                                   | T <sub>j</sub> = 150 °C | 3.0  |      |      | mJ   |
| R <sub>th(j-c)</sub>             | per diode                                                 |                         |      | 0.88 |      | K/W  |
| Module                           |                                                           |                         |      |      |      |      |
| L <sub>CE</sub>                  |                                                           |                         |      | 30   |      | nH   |
| R <sub>CC'+EE'</sub>             | terminal-chip                                             | T <sub>C</sub> = 25 °C  | 0.65 |      |      | mΩ   |
|                                  |                                                           | T <sub>C</sub> = 125 °C | 1    |      |      | mΩ   |
| R <sub>th(c-s)</sub>             | per module                                                |                         | 0.06 | 0.07 |      | K/W  |
| M <sub>s</sub>                   | to heat sink M5                                           |                         | 3    | 5    |      | Nm   |
| M <sub>t</sub>                   |                                                           | to terminals M5         | 2.5  | 5    |      | Nm   |
|                                  |                                                           |                         |      |      |      | Nm   |
| Weight                           |                                                           |                         |      | 170  |      | g    |

# S4G25T120SC9

## H bridge IGBT modules

### Features

- Trench Field Stop technology
- Ultra fast free wheeling diodes technology
- Low switching losses
- Switching frequency up to 30KHz
- Positive temperature coefficient for easy paralleling
- MOS input, voltage controlled

### Application

- AC and DC motor control
- AC servo and robot drives
- Power supplies
- Welding inverters

### Advantages

- space and weight savings
- reduced protection circuits

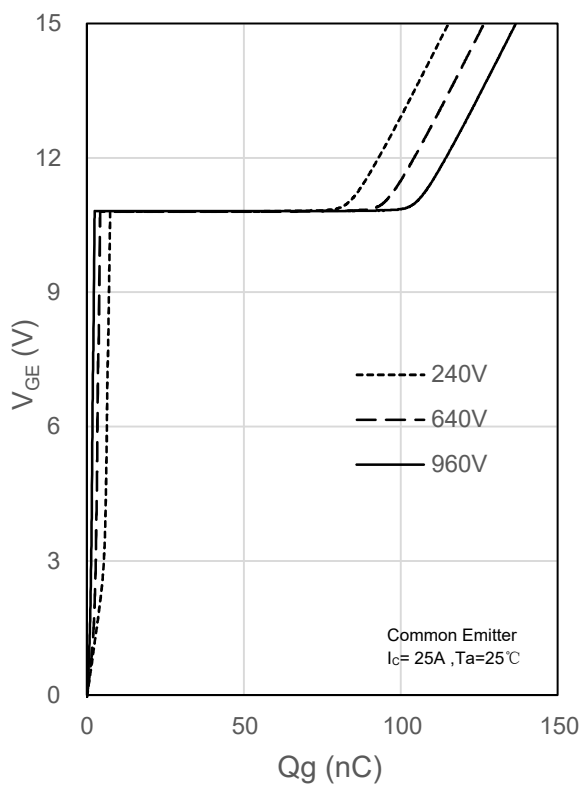


Fig. 1 Gate charge characteristics

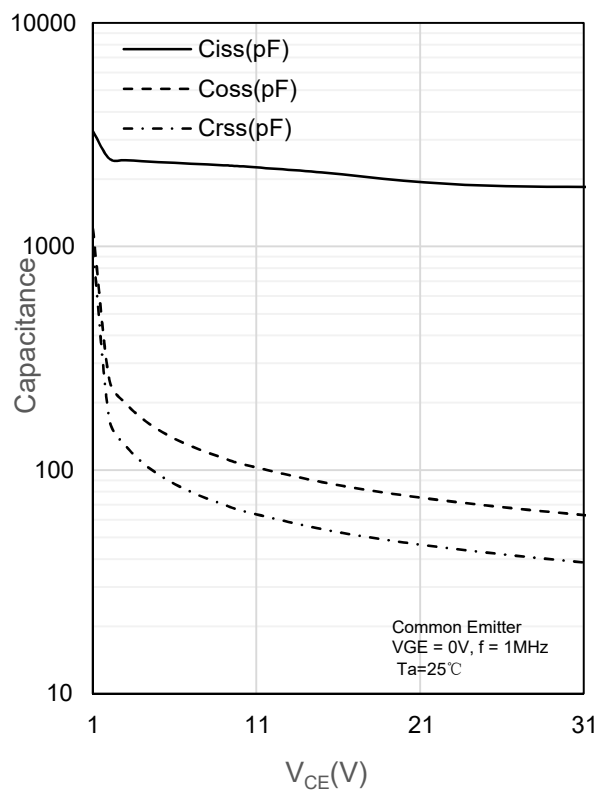


Fig. 2 Capacitance characteristics

# S4G25T120SC9

## H bridge IGBT modules

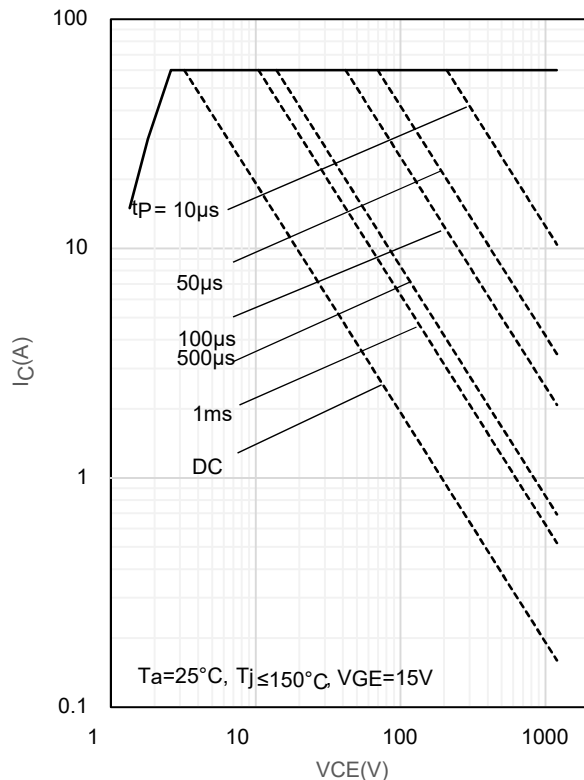


Fig. 3 FBSOA characteristics

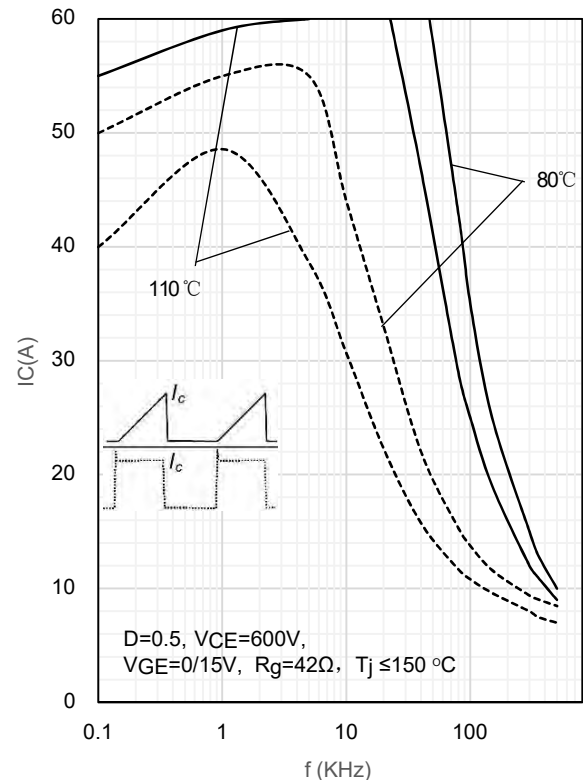


Fig. 4 Load Current vs. Frequency

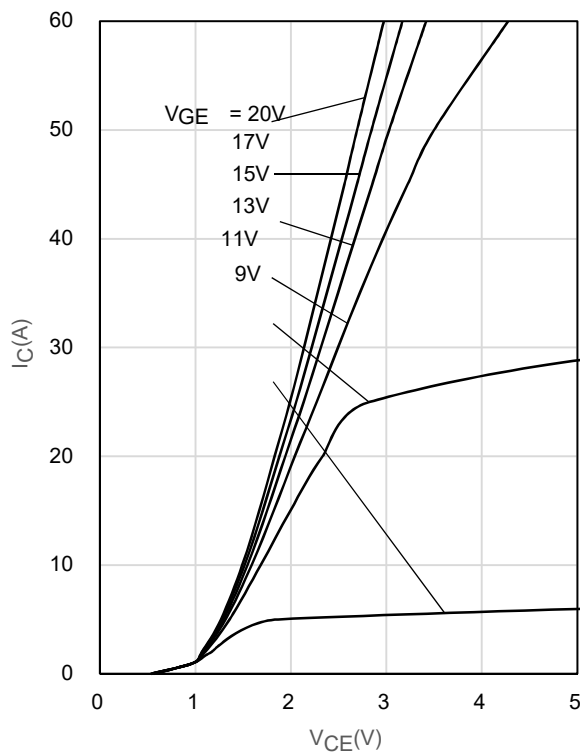


Fig. 5 Output characteristics

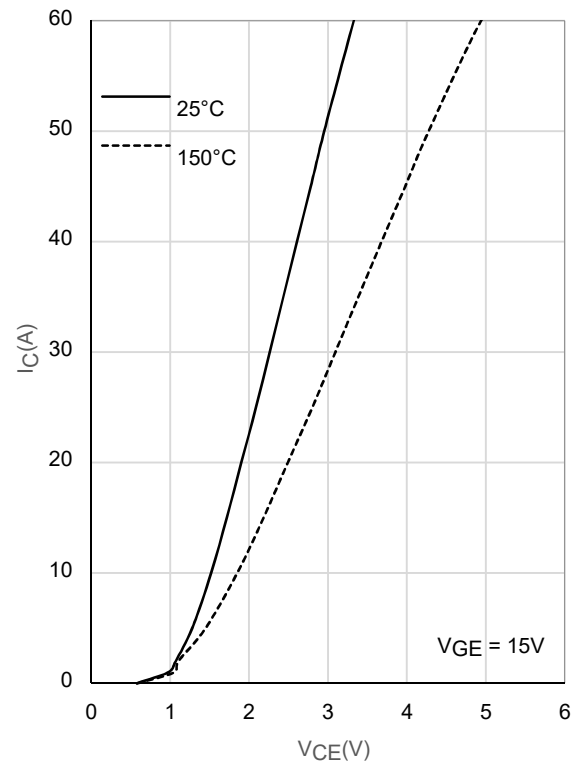


Fig. 6 Saturation voltage characteristics

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## H bridge IGBT modules

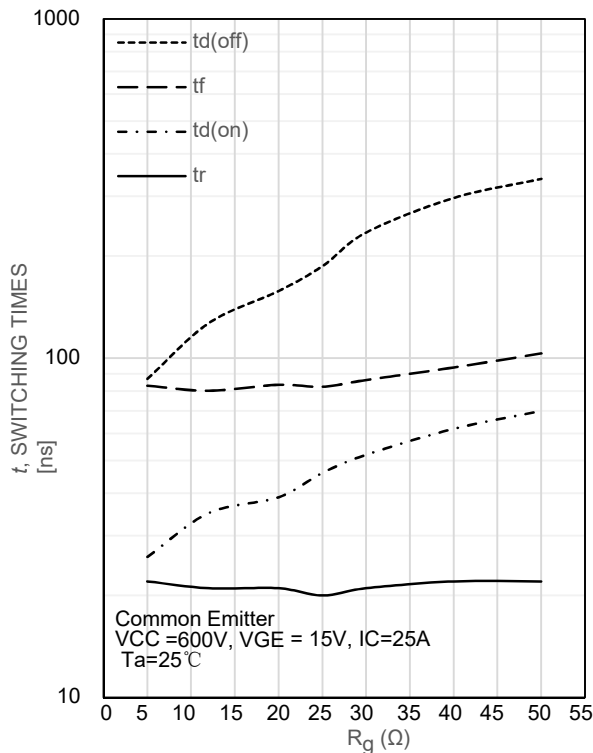


Fig. 7 Switching times vs. gate resistor

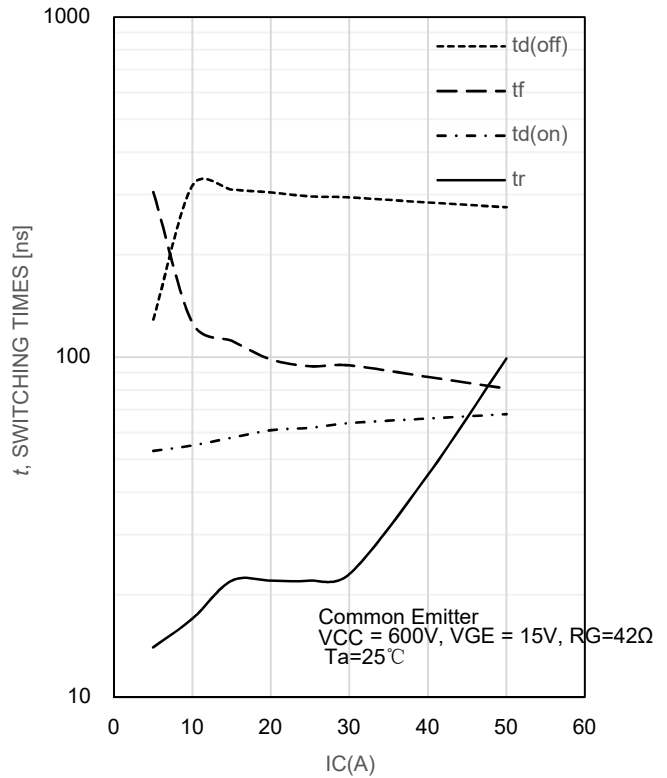


Fig. 8 Switching times vs. collector current

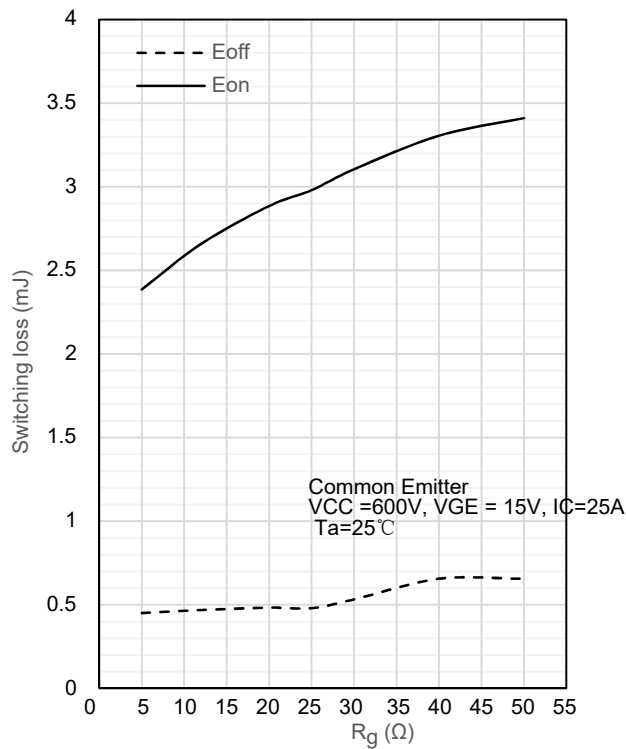


Fig. 9 Switching loss vs. gate resistor

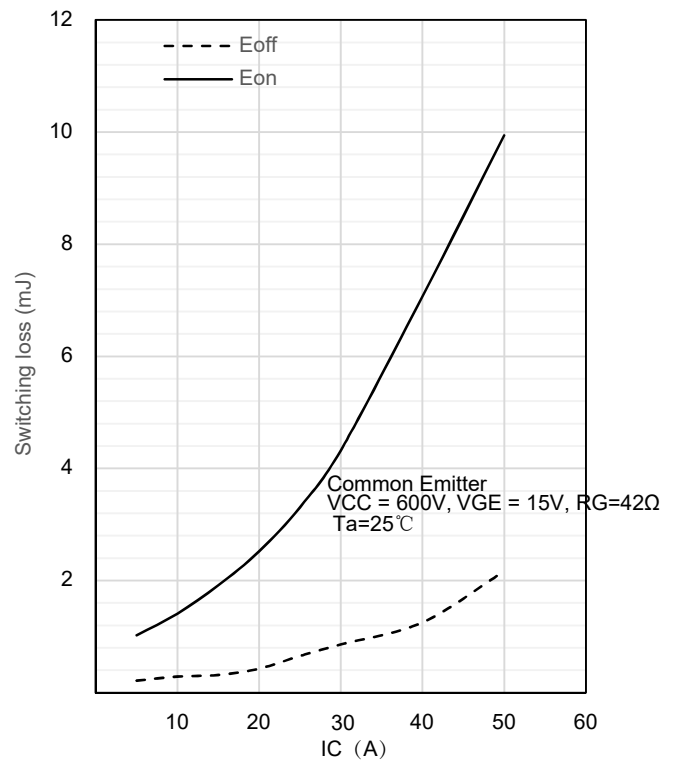


Fig. 10 Switching loss vs. collector current